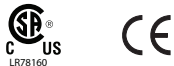


KHDSX Series Card Edge
High Density 0.050" (1.27mm) Spacing Card Edge

Features



- PCI (32 & 64 bit), AGP, and Microchannel Applications (MCA)
- Surface Mount Compatible Materials
- Visual and Mechanical Polarization
- CSA/NRTL Certified File No. LR78160

Performance Specifications

Materials and Finish

Body
High Temperature Thermoplastic, Glass Filled, UL 94V-0 Rated

Contact Material
Copper Alloy

Contact Finish
Gold Flash over Nickel on Contact Area

Electrical Characteristics

Rated Current
1.1A

Contact Resistance
30 milliohms Max.

Dielectric Withstanding Voltage
500V AC

Insulation Resistance
1000 Megohms Min after Exposure to Humidity

Mechanical Characteristics

Insertion Force
230g Max. Per Contact Pair

Extraction Force
15g Min. Per Contact Pair

Durability Test
50 Cycles

Operating Temperature
-10°C to +85°C

CARD EDGE CONNECTORS

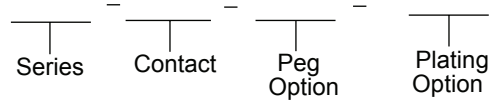
KHDSX Series

Documentation & Ordering Information

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Kycon Part #

Part Number Builder



Series

KHDSX - High Density 0.050" (1.27) Spacing

Contact

112 , 120 , 132 Pin

Peg Option

G - Plastic Peg

Plating Option

Blank - Gold Flash
15 - 15µ" Gold Plating
30 - 30µ" Gold Plating

Contact Kycon for More Pin Contact and Other Option

KHDSX Series Dimensions

Dimensions in mm

KHDSX-112-G

